

## Electronic Patent Application Fee Transmittal

Application Number:	10826985
Filing Date:	19-Apr-2004
Title of Invention:	Methods for forming protective layers on semiconductor device components so as to reduce or eliminate the occurrence of delamination thereof and cracking therein
First Named Inventor/Applicant Name:	Shijian Luo
Filer:	Brick Glenn Power/Sharley Thayne
Attorney Docket Number:	2269-5565.1US (02-1124.01)

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Filing a brief in support of an appeal	1402	1	510	510
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>510</b>